MALS068XG

Silicon planar type

For ESD protection

■ Overview

MALS068XG is optimal for cell phones and AV application, all types of I/O circuits.

It is possible to protect against forward and reverse surges.

■ Features

- High resistance to surge voltages: 15 kV guaranteed
- Low terminal capacitance C_t for low loss, low distortion, and good retention of signal waveforms.

■ Package

- Code
  SSMini2-F4
- Pin Name
  1: Cathode
  2: Cathode

■ Marking Symbol: RX

■ Absolute Maximum Ratings T_a = 25°C

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	I_{FRM}	200	mA
Total power dissipation *1	P_T	150	mW
Electrostatic discharge *2	ESD	±15	kV
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	-55 to +150	°C

Note) *1: P_T = 150 mW achieved with a printed circuit board.
*2: Test method: IEC61000-4-2 (C = 150 pF, R = 330 Ω, Contact discharge: 10 times)

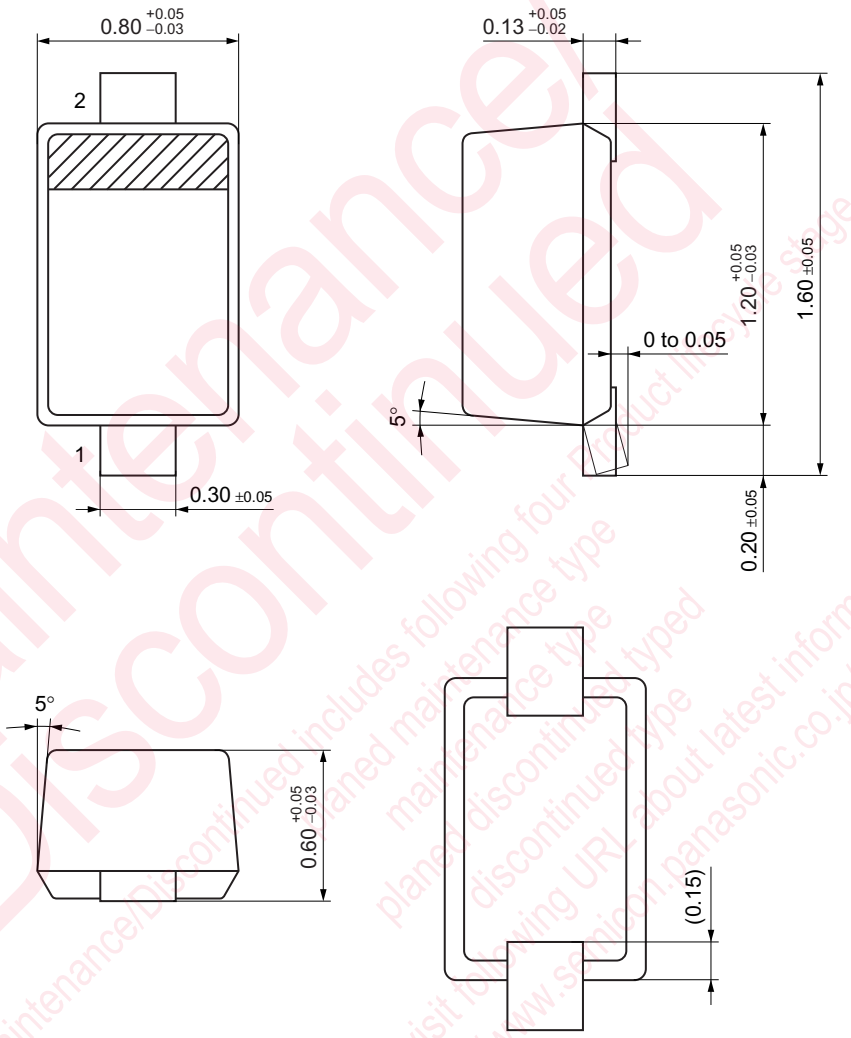
■ Electrical Characteristics T_a = 25°C±3°C

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Zener voltage *	V_Z	I_Z = 5 mA	6.5	7.0	7.5	V
Zene operating resistance	R_Z	I_Z = 5 mA			20	Ω
Reverse current	I_R	V_R = 4.0 V			50	nA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz		15		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. The temperature must be controlled 25°C for V_Z mesurement.
V_Z value measured at other temperature must be adjusted to V_Z (25°C)
3. *: V_Z guaranted 20 ms after current flow.

SSMini2-F4

Unit: mm



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